

CONTEMPORARY METALLIC MATERIALS

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Iskandar Idris Yaacob
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Edited by:

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Table of Content

Chapter 1 Upgrading of Laterite Ore by Reduction and Leaching <i>Hadi Purwanto and Pramusanto</i>	1
Chapter 2 Upgrading of Iron Sand by Magnetic Concentration and Reduction <i>Muta'alim, Hadi Purwanto, Nuryadi Saleh and Pramusanto</i>	7
Chapter 3 Microstructure and Mechanical Properties of Neutron Transmutation Doped of Silicon under Cf-252 Neutron Bombardment <i>Agus Geter Edy Sutjipto, Roslan Yahya</i>	16
Chapter 4 Effect of Stabilizer Addition on Crystal Formation of Zirconia Synthesize From Zircon Sand <i>Yuhelda Dahlan Hadi Purwanto, Nuryadi Saleh and Pramusanto</i>	20
Chapter 5 Upgrading of Iron-rich Laterite Ore Using Reverse Flotation <i>Hadi Purwanto, Mutaalim, Yuhelda Dahlan, Nuryadi Saleh and Pramusanto</i>	27
Chapter 6 Influences of Additives on Copper Film Quality and Gap Filling Capability of Plating Process <i>Shahjahan Mridha and Law Shao Beng</i>	34
Chapter 7 Grain Refining in AISI 430 Ferritic Stainless Steel Welds by Addition of Metal Powder <i>Shahjahan Mridha and Muhammed Olawale Hakeem Amuda</i>	41
Chapter 8 Grain Refinement Practices in Ferritic Stainless Steel Welds <i>Muhammed Olawale Hakeem Amuda and Shahjahan Mridha</i>	48
Chapter 9 Alloy Coating on Steel Surfaces by Melt Synthesis of Elemental Metal Powders <i>Shahjahan Mridha</i>	53

Chapter 10	59
Synthesis And Characterization of Lithium Manganese Copper Oxides for use in Lithium Rechargeable Cells	
<i>I.I. Yaacob, N. Kamarulzaman, and W.J. Basirun^f</i>	
Chapter 11	65
Influence of Grain Size on Magnetic Properties of Electroplated NiFe	
<i>Yusrini Marita and Iskandar Idris Yaacob</i>	
Chapter 12	70
Composite Coating on Titanium Alloy Using High Power Laser	
<i>Shahjahan Mridha</i>	
Chapter 13	75
The Tribological Behaviour of Al-Si Automotive Piston Material	
<i>Arifutzzaman and Md Abdul Maleque</i>	
Chapter 14	81
Conceptual Design of Folding Bicycle Frame with Light Weight Materials	
<i>Md Abdul Maleque and Mohd Nizam</i>	
Chapter 15	86
Reverse Engineering of Automotive Piston	
<i>Md Abdul Maleque and A. Arifutzzaman</i>	
Chapter 16	92
Recent Trend in Application of High Temperature Ferritic Fe-Cr Alloys in Power Plant	
<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	
Chapter 17	98
Measurement of Oxygen Permeability in Bulk Alloys by Internal Oxidation of Dilute Constituent	
<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	
Chapter 18	104
Recent Trend on Application of High Temperature Ferritic Fe-Cr Alloys in Solid Oxide Fuel Cells	
<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	
Chapter 19	110
Principle of Solid Electrolyte Oxygen Sensor	
<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	
Chapter 20	116
Surface Oxygen Potential on the Oxide Scale during High Temperature Oxidation of Fe-Cr Alloys at 1073 K	
<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	

	<i>Mohd Hanafi Bin Ani and Raihan Othman</i>	
Chapter 21		121
Reverse Engineering for Automotive Fuel Tank		
	<i>Md Abdul Maleque and Atiqah Afdzaluddin</i>	
Chapter 22		127
The possibility of utilizing scanning electron microscope for materials characterization		
	<i>Agus Geter Edy Sutjipto</i>	
Chapter 23		135
Piezoelectricity of Zinc Oxide Thin film as Source of Energy for Sensor Applications		
	<i>Agus Geter Edy Sutjipto, Liyana Abdul Gafar and Nor Azyati Syazwina Roselan</i>	
Chapter 24		141
Study on Zinc Oxide Crystal Growth		
	<i>Agus Geter Edy Sutjipto, Liyana Abdul Gafar and Nor Azyati Syazwina Roselan</i>	
Chapter 25		147
Green Nanotechnology using SEM and AFM		
	<i>A.G.E. Sutjipto and R. Muhida</i>	
Chapter 26		155
The effect of Cobalt addition on structural and magnetic properties of electrodeposited Iron-Platinum nanocrystalline thin films		
	<i>Seoh Hian Teh¹, Iskandar Idris Yaacob</i>	
Chapter 27		163
Mechanochemical Synthesis of CeO ₂ Nanopowder using Planetary Ball Milling		
	<i>Iskandar I. Yaacob</i>	
Chapter 28		170
A Study on Double Junction Zinc Based/Polymer Thin Film Solar Cell		
	<i>S. A. Mohamad and A. K. Arof</i>	
Chapter 29		176
A Voltammetric Study of Zinc Telluride Thin Films Prepared for Photovoltaic Applications		
	<i>S. A. Mohamad and A. K. Arof</i>	
Chapter 30		181
Electrodeposition Technique for ZnO Semiconductor Thin Films Fabrication		
	<i>S. A. Mohamad</i>	
Chapter 31		186
Electroless Nickel Based Coatings From Solution Containing Sodium Hypophosphite		
	<i>Suryanto</i>	

Chapter 32 Aluminum Spray Coating for Corrosion Resistance of Steel	192
	<i>Suryanto</i>
Chapter 33 Electrodeposition of Alloys	198
	<i>Suryanto</i>
Chapter 34 Corrosion Behavior of Duplex Stainless Steel in Sea Water	204
	<i>Suryanto</i>
Chapter 35 Cathodic Protection of Underground Pipes	210
	<i>Suryanto</i>

Influences of Additives on Copper Film Quality and Gap Filling Capability of Plating Process

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Keywords: Electroplating, Copper, Silicon wafer, Electrolyte, Additives, Gap filling, Grain

Abstract: In this work, investigations of the effect of additives such as suppressor (S) and accelerator (A) on the deposition rate and gap filling capability of plating process were carried out by cyclic voltammetry stripping (CVS) analysis, FIB, TEM and FESEM. In addition, the impact of additives on physical characteristics of electroplated Cu film was also studied. We found that CVS analysis was very useful in predicting and explaining the change of the plating process with different electrolytes. Cu film with big grain, rough surface finish, and poor gap filling was observed for Cu sulfate electrolyte (CSE). Addition of A alone has minimum effect in altering the plating process. Addition of S alone, however, changes both the plating process and Cu film characteristics. If the plating is done in CSE with both S and A, the electroplating process gives bottom up growth (BUG) and the Cu film consists of very fine grain microstructure with a very smooth surface. We also observed that the onset of the BUG process and BUG rate are strongly dependent on the concentrations of S and A.

Introduction

Cu electroplating has become a critical metallization process for the next generation IC device fabrication. It provides bottom up gap filling capability, high throughput and low cost of ownership [1-3]. As reported [4-8], with appropriate amounts of S and A, it can alternate the bottom up growth (BUG) process and lead to void free gap filling. Many researchers [9-12] have suggested different models to explain this BUG phenomena. In this paper, an in-depth characterization study is performed to understand the impact of different electrolytes on the deposition rates and the physical properties of Cu film plated on blanket barrier surfaces. These findings are also used to examine and to understand the gap fill capability of different electrolytes.

Experimental

In this work, electrolytes such as CSE, A_x + CSE, S_y + CSE and A_x + S_y + CSE were mixed and characterized using CVS technique. Among the electrolytes, CSE, 1ml/l A + CSE, 25ml/l S + CSE, 1ml/l A + 25ml/l S + CSE, 10ml/l A + 25ml/l S + CSE and 1ml/l A + 40ml/l S + CSE were used. This study was mainly focused on the Cu film properties and gap fill capability using contact opening with 2.5:1 aspect ratio and 0.2μm wide trenches. The Cu film was plated on 2cm x 2cm samples with 2000Å Cu seed/ 300Å TaN barrier/ 5000Å undoped SiO₂/ Si substrate. A current density of 10mA/cm², stirring rate of 400 rpm, and various plating times (10, 30 and 120s) at room temperature was applied for the plating process in a laboratory scale electroplating system. The grain size and surface morphology of